

Elephantech Benefits from Startup Debt Guarantee Scheme to Sign Loan Agreement Totaling 2 Billion Yen

Elephantech Inc (“Elephantech”) is pleased to announce that it has recently signed a loan agreement for a total of two billion yen by utilizing the Innovative Technology Research Results Utilization Facilitation Debt Guarantee System (“Debt Guarantee System”) provided by the Independent Administrative Institution, Organization for Small & Medium Enterprises and Regional Innovation, JAPAN (“SME Support JAPAN”).

The Innovative Technology Research Results Utilization Facilitation Debt Guarantee System is a program under which deep technology, large-scale R&D-based venture companies certified under the Ministry of Economy, Trade and Industry's Innovative Technology Research Results Utilization Business Plan can obtain debt guarantees from the SME Support Japan when borrowing funds to establish mass production capabilities from private financial institutions designated by the METI. Prior to this contract, Elephantech received certification from the METI for its business activity plan for the utilization of innovative technology research results. As a result, under the SME Support Japan's Debt Guarantee System, Elephantech received a guarantee rate equal to 50% of the loan amount, and subsequently entered into a loan agreement with Mizuho Bank, Ltd. for a total of two billion yen.

By utilizing these funds, Elephantech aims to further strengthen its PCB manufacturing capabilities and accelerate sales expansion in the global market.

Debt Guarantee Overview

Date of Loan Agreement	December 22, 2023
Lending Financial Institution	Mizuho Bank, Ltd.
Loan Amount	2 billion yen
Loan Period	5 years for working capital, 7 years for equipment investment
SME Support Japan's Guarantee	50% of the borrowing principal (1 billion yen)

Related Links:

<https://www.meti.go.jp/policy/newbusiness/debt/tps/tuika/zentaigaiyou.pdf>

<https://www.smrj.go.jp/sme/funding/guarantee/>



About Elephantech

Elephantech is a startup company that uses metal inkjet printing to produce low-carbon Printed Circuit Boards(PCB). Its P-Flex® PCB product features a 75% reduction in CO2 emissions and a 95% reduction in water consumption compared to equivalent products produced by conventional production methods. P-Flex® is used in a wide range of applications, including computer peripherals and sensors.

Through the proliferation of our low environmental impact PCBs, we aim to contribute to the decarbonization and reduction of environmental impact within the electronics industry.

Company Overview

Name	Elephantech Inc.
Establishment	January 2014
Headquarters	4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan
Representative	Shinya Shimizu, Representative Director & CEO
Business Description	Development of printed electronics manufacturing technology and provision of related services
URL	https://www.elephantech.co.jp/en/

Contact for inquiries regarding this matter
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